



微信号：sinictek  
热线：400-0755-021



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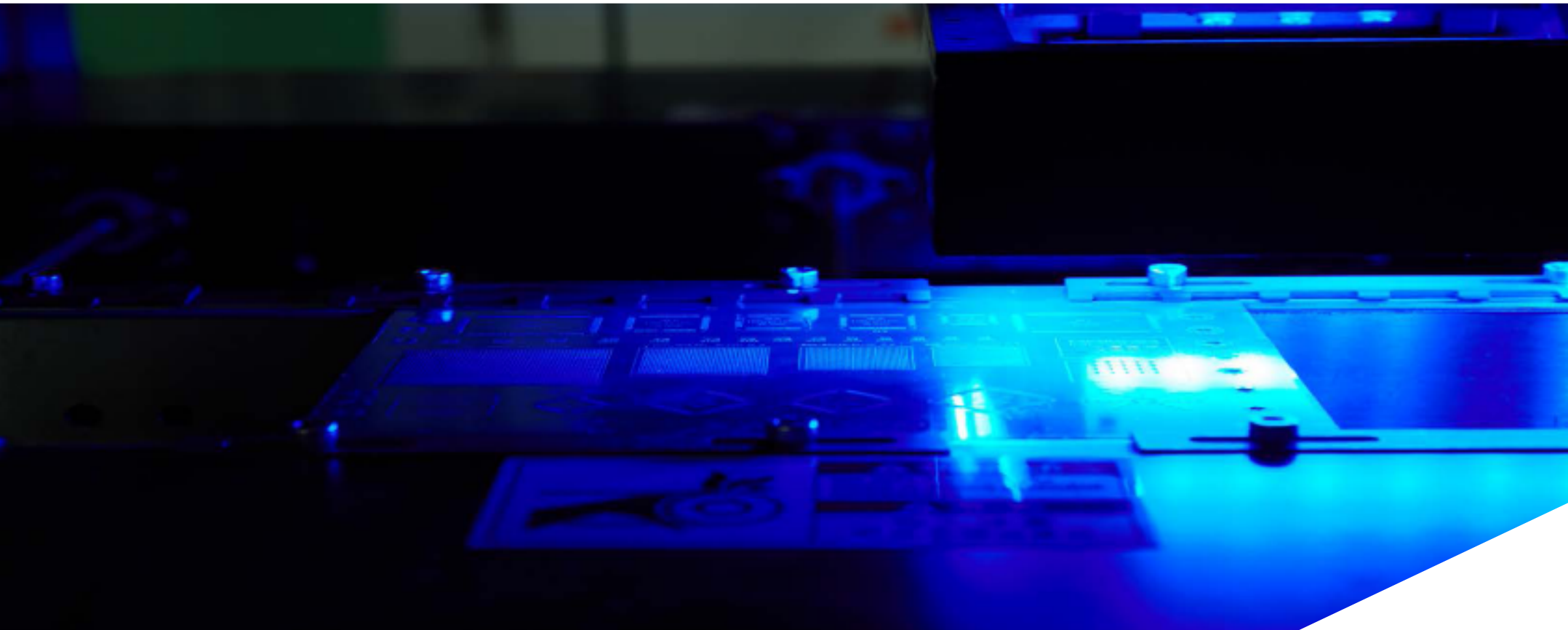


股票代码：839448



SINIC-TEK INTELLIGENT  
TECHNOLOGY CO., LTD.

**SINIC-TEK**  
**INTELLIGENT**  
**TECHNOLOGY**



# COMPANY PROFILE

## 公司概况

厦门思泰克智能科技股份有限公司 (Sinic-Tek Intelligent Technology Co., Ltd) 主要以电子装配行业 (PCBA) 制造和半导体 (Semiconductor) 制造中的三维无损光学检测系统软 / 硬件的开发、生产、销售及增值服务为主营。

厦门思泰克智能科技股份有限公司于 2016 年 11 月 1 日正式登陆由中国证监会和科技部组织的新三板股份转让系统，【股票代码：839448】。

思泰克公司汇集了有十多年电子装配行业技术研究经验的工程师及开发人员，以世界先进技术为基础，不断研发新型高精度无损检测系统。

思泰克公司推出的 T 系列桌面型高速三维锡膏检测系统包含了 T-1010a, T-2010a, T-3010a, 全方位满足不同客户的需求。InSPIre 系列, S 系列和 F 系列在线型高速三维锡膏检测系统的高速, 高精度, 全功能, 简易操作的设计已经得到广大客户的赞誉。Ultra 系列超高速, 超高精度在线型高速三维锡膏检测系统将全方位的达到国际一流设备的性能。

思泰克公司的全部人员将以“新技术, 新服务, 新发展”为理念, 建立中国自主品牌的具有世界一流水平的电子装配检测系统。

Xiamen Sinic-Tek Intelligent Technology Co., Ltd. is mainly specialised in the software/hardware development, production, sales and value added services of 3D Solder Paste Inspection (SPI) for PCBA & semiconductor manufacturing industry.

2016/11/1, Xiamen SinicTek Intelligent Technology Co., Ltd. successfully went public on "National Equities Exchange and Quotations" (NEEQ) organized by China Securities Regulatory Commission & Ministry of science and technology. [Stock Code: 839448]

The Sinictek T series desktop high speed SPI system including T-1010a, T-2010a, T-3010a, will meet most of client's needs. The inSPIre series, S series and F series inline high speed SPI system is featured in high speed, high precision, full function and simple operation design which received recognitions from various customers. Ultra series incline high speed SPI system with ultra high speed and ultra high precision will reach world class performances in every aspects.

Sinictek is aimed to build global leading PCBA inspection system with China own brand, all our staff would follow the concept of "New Technology, New Service, New Development".

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厦门思泰克智能科技股份有限公司大楼  
Company Building of Sinic-Tek Intelligent Technology in Xiamen



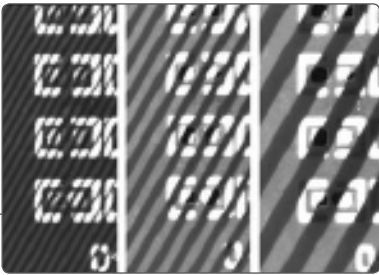


High Efficiency, High Speed, Stability  
高效 快速 稳定

可编程结构光栅技术 (PSLM)  
PROGRAMMABLE SPATIAL LIGHT MODULATION

独创的可编程结构光栅使用软件即可对光栅的周期进行调制。取消了机械驱动及传动部分，大大提高了设备的精度及适用范围（检测高度可达  $\pm 1200\mu\text{m}$ ），避免了机械磨损和维修成本。

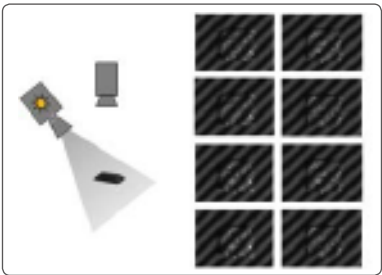
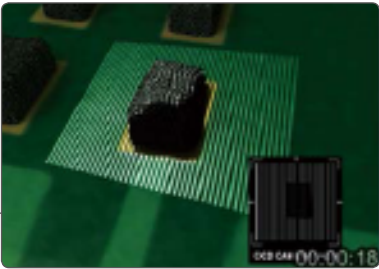
The original PSLM technology emulates the cycle of the optical grating by using software. This greatly improves the accuracy and scope of application by abolishing the mechanical drive and transmission parts. (The detection height can reach to  $\pm 1200\mu\text{m}$ ) and avoids mechanical wear and maintenance costs.



相位调制轮廓测量技术 (PMP)  
PHASE MODULATION PROFILERMETRY

通过全色光的相位调制，提供了超高的检测分辨率 ( $0.37\mu\text{m}$ )，4 至 8 次的采样数量保证了超高的重复性精度。配合高精度的丝杆和导轨达到完美的检测效果。

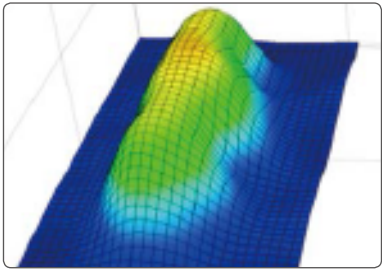
Through the phase modulation of full light spectrum, provide a height resolution down to ( $0.37\mu\text{m}$ ), the number of 4-8 times sampling ensure high repeatability. Use high-precision ball screw and linear guide rail to realize perfect detection result.



同步结构光技术 (D-Lighting)  
RGB Tune 二维光源的完美配合

同步结构光的使用完美解决锡膏检测中阴影部分的影响。结合专利的 RGB Tune 功能完美处理高对比度的基板，如黑色基板，陶瓷基板等。并完美的解决桥接误判和相对基准面不确定的问题，并同时提供 2D/3D 彩色的锡膏图片。

Usage of synchronized structure light perfectly solves the shadows effect in the solder paste inspection. Combined with RGB dimensional light source, it perfectly provides high-contrast substrate on all substrates. Such as the black substrates, ceramic substrates, and provides the paste pictures of coloured 2D/3D.



有源真彩色二维光源 (RGB Tune)  
ACTIVE RGB 2D LIGHT SOURCE

专利的 RGB Tune 功能通过单独拍摄红绿蓝三原色照片并结合独特的颜色过滤算法，完美的解决桥接误判和相对基准面不确定的问题，并同时提供 2D/3D 测量结果和彩色的锡膏图片。

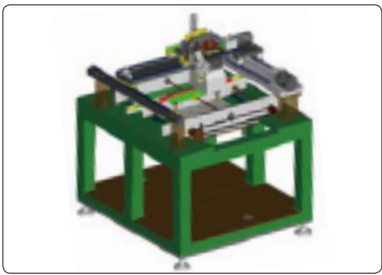
Patented RGB Tune function takes Red, Green and Blue images and with unique filter algorism, to solve solder bridge detection false alarm and relative zero surface uncertain issue. In the mean time, provide the 2D/3D measurements and image of printed solder paste.



高解析度图像处理系统  
HIGH RESOLUTION AND HIGH FRAME RATE  
IMAGE PROCESSING UNIT

超高帧数百万像素（可选不同像素）工业 CCD 确保对极小型元件及高密度贴装 (03015) 进行稳定快速的检测。提供  $10\mu\text{m}$ ,  $12\mu\text{m}$ ,  $15\mu\text{m}$ ,  $18\mu\text{m}$ ,  $20\mu\text{m}$  等多种不同的检测精度。配合客户的产品多样性和检测速度的要求。

Megapixel industrial CCD camera of ultra-high frame rate ensure a steady and rapid detection of very small components and high-density mounting (03015). It provides a variety of detection accuracy of  $10\mu\text{m}$ ,  $12\mu\text{m}$ ,  $15\mu\text{m}$ ,  $18\mu\text{m}$ ,  $20\mu\text{m}$  etc. It meets the customer's requirements for product diversity and detection speed.



高精度一体式控制平台  
HIGH ACCURATE HARDWARE PLATFORM

高强度的钢制一体式结构，标配的伺服电机配合高精度研磨级滚珠丝杆及导轨，运动高速，平稳。选配的直线电机和高精度光栅尺可以对 03015 元件锡膏进行超精准的快速测量，重复精度可以达到  $1\mu\text{m}$ 。

High rigid grade steel frame combines with close loop servo control and high precision level ball screw makes high speed and steady positioning. Optional linear and high precision linear encode positioning system is capable measure 03015 device pad with ultra high resolution and high speed. The repeatable accuracy can down to  $1\mu\text{m}$ .



Z 轴实时动态补偿和视觉静态补偿能力  
Z AXIS REAL TIME AND STATIC VISION  
COMPENSATION CAPABILITY

PSLM 的特点提供了对 PCB 的翘曲变化进行实时动态跟踪，配合特殊的高解析度镜头完美解决柔性线路板和 PCB 翘曲问题。

The characteristics of PSLM provides real-time dynamic tracking on change of the PCB warpage, and perfectly solves the problems of flexible circuit boards and PCB ware page.

# PRODUCT FEATURES

## 五分钟编程和一键式操作 5 MINUTES PROGRAMMING AND ONE PRESS OPERATION

通过导入 Gerber 模块和友好的程序编制界面，使得任何水平的工程师都可以独立快速准确的进行编程编制。对于操作人员设计的一键式操作也大大减轻了培训压力。

Engineers with any levels of experience can independently program the system quickly and accurately through Gerber importing software module and the friendly programming interface. One-button operation by the operator is designed also greatly reduces the requirements for training.

## 强大的过程分析 (SPC) POWERFUL STATISTIC PROCESS CONTROL SOFTWARE

实时 SPC 信息显示，提供给使用者强有力的品管支持。完整多样的 SPC 工具，让使用者一目了然。并支持不同格式的数据输出。

Real-time SPC information display, provides powerful quality control to the users. Complete variety of SPC tools, are available for users at a glance.

## 同轴基准点相机单元 Coaxial Lighting Mark Camera Unit

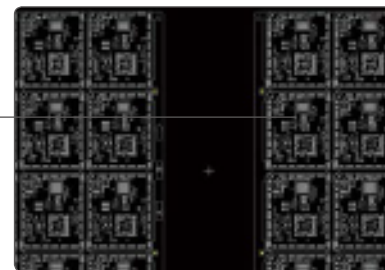
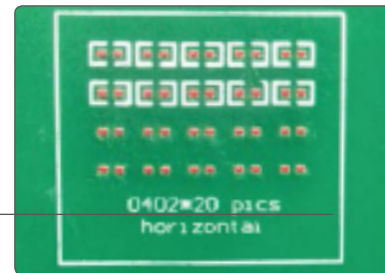
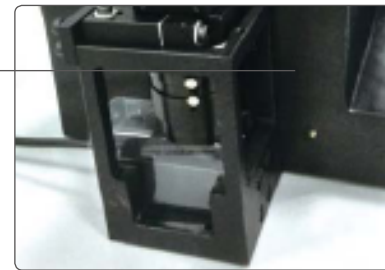
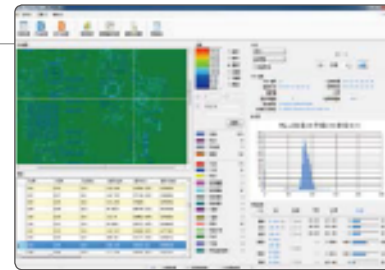
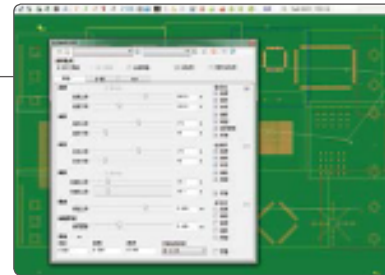
选配的同轴基准点相机单元可以准确识别喷锡板，镀金板，柔性线路板等不同材质的基准点。

Optional coaxial lighting mark camera unit can reliable and precise detect fiducial mark on HASL, shining gold and flex PCB surface.

## 胶水检测 GLUE INSPECTION

可编程结构光栅 (PSLM) 的特性使得最大检测高度可以到达  $\pm 1200\mu\text{m}$ ，结合 RGB Tune 技术可以对非透明类的胶水工艺进行高精度的三维检测，包括漏印，溢印，多胶，少胶，形状不良，并显示真彩色的二维及三维图像。

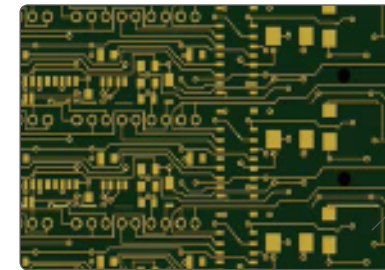
PSLM 3D measurement can reach  $\pm 1200\mu\text{m}$ , with RGB Tune function is capable of high accurate measuring of none transparent glue process, include missing, overflow, excess, shape and combination view of 2D/3D images



## 配合印刷机的闭环控制 (Close-Loop) Close Loop with Printer

共享实时检测数据给印刷机并实时调整印刷工艺。

Share real time measurement result with printer, and adjust printer parameter in time automatically.



## 坏板飞行识别功能 (Bad-Mark) Bad Mark On The Fly Detection

自动准确的识别坏板标记，并实时反馈到贴片机。

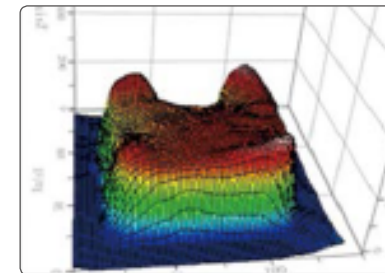
Automatically on the fly detect PCB bad mark, feed the info into pick and placement machine in real time control loop.



## 多样化的条码识别功能 (Bar-Code Recognition) MULTI OPTIONAL BARCODE FUNCTION

可以选用主相机或外置条码读取装置读取一维及二维条码，并支持手工输入条码功能。

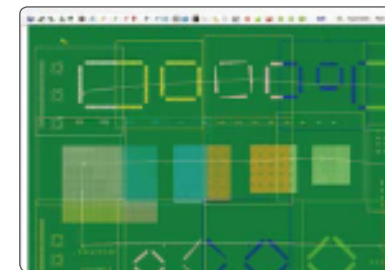
Both camera barcode and external 1D/2D barcodes are supported, also provide manual key in function.



## 三点照合 (Traceability) THREE STAGE MAPPING TRACEABILITY

配合不同的炉前 AOI 和炉后 AOI 等 SMT 生产线上的检测设备，形成全闭环的品质控制体系。并可以将数据同步到 ERP 等质量控制系统中去。

Collaborate with pre and post AOI equipment in SMT line, forms close loop process and quality control system. And capable to integrate and synchronize the data to customer ERP quality module.



## 离线编程 OFF-LINE PROGRAMMING

通过离线编程软件导入 Gerber，一键式 CAD 数据拼接。

Provide offline Gerber import function, one button CAD matching function.



丰富多样的在线型平台  
Online platform rich

InSPIre 系列、S 系列、F 系列在线设备除了标准 A 平台及标准 B 平台以外，还提供超大板及双轨平台，多投影头配置。

InSPIre series, S series, F series inline machine provide not only standard A and B platform, but also ultra large size and dual lane with multi projection head configuration.



新技术引领新发展

Product Features

- Usage of PSLM combined with the PMP achieves 100% high-precision solder paste 3D measurement in SMT production line. Usage of PSLM technology changed the traditional way of generating structured light, because the traditional glass grating moire (Moiré) requires mechanically drive by a piezoelectric motor (PZT).
- By using PSLM, there is no need for glass grating and mechanical parts any more. The elimination of the mechanical drive and moving parts greatly improves the ease of use and avoids mechanical wear and reduce maintenance costs.
- Ultra-high frame rates and high dynamic range industrial 4 megapixels cameras, together with the high precision grade balls-crew and guide rail mechanical structure, guarantee for high-speed and stable measurement.
- Patented 3D DL (Diffuse lighting) technology, combined with 2D RGB light source, achieve easiness of use. It is a perfect solution to solve the shadow effect and to reduce the noise interference in 3D measurement.
- Gerber data conversion and import, achieve automatic detection of the entire board. Manual "Teach" function realizes user-friendly programming and test job generation in case of no Gerber data situation.
- The maximum detectable height was increased from the traditional.± 350um to ± 1200um, so it not only can detect solder paste, but also applies to the detection of opaque objects such as red glue and black epoxy and other none transparent object.
- Friendly and simple user interface, five minutes of programming needed and one key operation.
- Powerful "Statistical Process Control (SPC)", provide a plenty of tools, user-friendly real-time monitoring of production, reduce defects caused by poor solder paste printing and improve customerproduct quality.
- PCB size up to 480 × 450mm, can be widely used in themanufacturing of electronic products, in the application range like: mobile phones, digital products, television, audio and video appliances, computer accessories, automotive electronics, medical electronics, LED, etc.

产品特点

- 运用可编程结构光栅（PSLM）结合相位调制轮廓测量技术（PMP）实现对 SMT 生产线中精密印刷焊锡膏进行 100% 的高精度三维测量。
- 可编程结构光栅（PSLM）的应用，从此改变了传统由陶瓷压电马达（PZT）驱动摩尔纹（Moiré）玻璃光栅的形式。取消了机械驱动及传动部分，大大提高了使用的便捷性，避免了机械磨损和昂贵的维修成本。
- 高精度超高帧数的四百万像素工业相机，配合精密的研磨级丝杆和导轨，实现高速稳定的检测。选配的 1200 万像素和磁悬浮驱动可以应对 SMT 应用中的极端技术要求。
- 采用专利技术的 D-Lighting 结合专利的 RGB Tune 光源不仅的完美解决了三维测量中的阴影效应干扰，还能有效的避免常规锡膏检测中的常见的锡膏桥接误判和基准面不准的问题。
- 在线型 InSPIre 和 S 系列设备可以灵活的配置不同的方案对应单轨，双轨，单头，多头等丰富多样化的客户要求。
- Gerber 数据转换及导入，实现全板自动检测。人工 Teach 功能方便使用者在无 Gerber 数据时的编程及检测。
- 最大可检测高度由传统的 ±350um 增加到 ±1200um，不仅可以检测锡膏，也适用于红胶和黑胶等不透明物体的检测。
- 友好简洁的操作界面，实现五分钟编程一键式操作。
- 强大的过程统计软件（SPC），提供丰富的工具，方便使用者实时监控生产中的问题，减少由于锡膏印刷不良造成的缺陷，从而有效的提升产品质量。
- 适用小于 480×450mm 电路板的锡膏检测，可在电子产品生产制造中广泛使用，对应产品类别有：手机、数码产品、电视、影音电器、电脑配件、汽车电子、医疗电子、LED 等。

| 技术参数 / Parameters                                  |   |                             |                          |                              |                                    |
|--|---|-----------------------------|--------------------------|------------------------------|------------------------------------|
| 平台 Platform  | 单轨 A / B / 超大板平台  |                             | 双轨平台                     |                              | 超大板平台                              |
| 适用系列 Series  | InSPIre 系列 /S 系列 /F 系列  |                             | InSPIre 系列 / S 系列        |                              | InSPIre 系列 / S 系列                  |
| 型号 Model   | 510 / 630 / 8030  |                             | 450DL / 630DL            |                              | 1200                               |
| 测量原理 Measurement Principle                         | 3D 白光 PSLM PMP （可编程结构光栅相位调制轮廓测量技术）  |                             |                          |                              |                                    |
| 测量项目 Measurements                                  | 体积，面积，高度，XY 偏移，形状   |                             |                          |                              |                                    |
| 检测不良类型 Detection of Non - Performing Types         | 漏印，少锡，多锡，连锡，偏移，形状不良   |                             |                          |                              |                                    |
| 视野尺寸 FOV Size                                      | 36 X 36mm（基于 4M 像素 /18um 解析度）：10um/15um/18um/20um/22um/25um 可选  |                             |                          |                              |                                    |
| 精度 Accuracy  | XY 方向：10um；高度：0.37um  |                             |                          |                              |                                    |
| 重复精度 Repeatability                                 | 高度：小于 1um （4 Sigma）；体积 / 面积：小于 1%（4 Sigma）  |                             |                          |                              |                                    |
| 检测重复性 Gage R&R                                     | 远远小于 10%  |                             |                          |                              |                                    |
| 检测速度 Inspection Speed                              | 0.35 秒 /FOV   |                             |                          |                              |                                    |
| 检测头数量 Quantity of Inspection Head                  | Single Head （Twin-Heads* 选件；Tri-Heads* 选件）  |                             |                          |                              |                                    |
| 基准点检测时间 Mark-point Detection Time                  | 0.3 秒 / 个   |                             |                          |                              |                                    |
| 最大检测高度 Maximun Measuring Height                    | ±350um （±1200um * 选件）   |                             |                          |                              |                                    |
| 弯曲 PCB 最大测量高度 Maximum Measuring Height of PCB Warp | ±5mm  |                             |                          |                              |                                    |
| 最小焊盘间距 Minimum Pad Spacing                         | 100um （焊盘高度为 150um 的焊盘为基准）  |                             |                          |                              |                                    |
| 最小测量大小 Smallest Size Measurement                   | 长方形：150um；圆形：200um  |                             |                          |                              |                                    |
| 最大 PCB 载板尺寸 Maximum Loading PCB Size               | X510 x Y505mm；X630 x Y550mm   |                             | X450 x Y310 mm           | X630 x Y310mm                | 单次 x600*y550mm<br>两次测 x1200*y550mm |
| 定动轨设置 Conveyor Setup                               | 前定轨（后定轨 * 选件）   |                             | 1 定轨，2.3.4 动轨            |                              | 前定轨（后定轨 * 选件）                      |
| PCB 传送方向 PCB Transfer Direction                    | 左到右；右到左   |                             |                          |                              |                                    |
| 轨道宽度调整 Conveyor Width Adjustment                   | 手动和自动（前定轨或后定轨）  |                             |                          |                              |                                    |
| 工程统计数据 Engineering Statistics                      | Histogram; Xbar-R Chart; Xbar-S Chart; CP&CPK; %Gage Repartability Data; SPI Daily/Weekly/Monthly Reports |                             |                          |                              |                                    |
| Gerber 和 CAD 导入 Gerber & CAD Data Import           | 支持 Gerber 格式（274x，274d）；人工 Teach 模式；CAD X/Y，Part No.，Package Type 等导入                                     |                             |                          |                              |                                    |
| 操作系统支持 Operating System Support                    | Windows 7 Professional （64 位）   |                             |                          |                              |                                    |
| 设备规格 Equipment Diemension and Weight               | 1000 x 1000 x 1560mm; 865KG   | 1000 x 1350 x 1560mm; 985KG | 1155x1350x1560mm; 1350KG | 1890 x 1331 x 1560mm; 1130KG |                                    |
| 选配件 Optional                                       | 1D/2D Barcode 扫描枪；Badmark 功能；印刷机闭环控制；离线编程；维修工作站；胶水检测套件；同轴 Mark 点相机；UPS 不间断电源                              |                             |                          |                              |                                    |

丰富多样的离线型平台  
The off-line platform rich

T 系列桌面型设备提供中型，大型及超大型平台配置。

T series table top equipment provide medium, large and ultra large size platform configuration.



Product Features

- The use of PSLM combined with the PMP to achieve 100% high-precision solder paste 3D measurement in SMT production line.
- Usage PSLM technology, changed the traditional way of generating 3D Struct Light, the traditional glass grating moire (Moiré) required mechanically driven by a piezoelectric motor (PZT). By using PSLM, there is no need for glass grating and mechanical parts any more.The elimination of the mechanical drive and moving parts, greatly improves the ease of use and avoid mechanical wear and reduces maintenance costs.
- Stop & Catch methods combined with multiple image acquisition realize highly repeatable 3D results in the solder paste measurement. Compared to conventional scanning, it is just takes one pictures of the solder paste every scan sampling only, while multiple image acquisition greatly enhance the accuracy and reliability of test results.
- Patented DL technology achieves full light spectrum detecting ability. It is the perfect solution to solve the shadow effect and reduce noise interference during the 3D measurement.
- Gerber data conversion and import achieve automatic detection of the entire board. Manual "Teach" functions realize user-friendly programming and test job generation in case of a no Gerber data situation.
- The maximum detectable height has thus increased from the traditional  $\pm 350\mu\text{m}$  to  $\pm 1200\mu\text{m}$ , so it can only not detect solder paste, but also is applicable to the detection of opaque objects such as red glue and black epoxy and other none transparent objects.
- Friendly and simple user interface, five minutes of programming and one key to operation.
- Powerful "Statistical Process Control (SPC)", provides a plenty of tools, user-friendly real-time monitoring, reduces defects caused by poor solder paste printing and improve final product quality.
- Fit for up to  $350 \times 250\text{mm}$  PCB, the application range for like: mobile phones, PC, digital cameras, camcorders, computer accessories,etc.

产品特点

- 运用可编程结构光栅（PSLM）结合相位调制轮廓测量技术（PMP）实现对 SMT 生产线中精密印刷焊锡膏进行 100% 的高精度三维测量。
- 可编程结构光栅（PSLM）的应用，从此改变了传统由陶瓷压电马达（PZT）驱动摩尔纹（Moir é）玻璃光栅的形式。取消了机械驱动及传动部分，大大提高了使用的便捷性，避免了机械磨损和维修成本。
- 采用步进检测（Stop & Catch）结合多次采样的方式，即在运动停止时对焊膏进行多次拍照采样处理，相比常规扫描方式（Scanning）在运动中拍照只对焊膏进行一次扫描采样，大大增强了检测结果的准确性和可信性。
- 采用专利技术的 DL 结合易于调节的全色光谱完美解决三维测量中的阴影效应干扰。
- 编程采用 Gerber 数据转换及导入形式，实现全板自动检测。人工 Teach 功能方便使用者在无 Gerber 数据时的编程及检测。
- 最大可检测高度由传统的  $\pm 350\mu\text{m}$  增加到  $\pm 1200\mu\text{m}$ ，不仅可以检测锡膏，也适用于红胶和黑胶等不透明物体的检测。
- 友好简洁的操作界面，实现五分钟编程一键式操作。
- 强大的过程统计软件（SPC），提供丰富的工具，方便使用者实时监控生产中的问题，减少由于锡膏印刷不良造成的缺陷，从而有效的提升产品质量。
- 适用小于  $350 \times 250\text{mm}$  电路板的锡膏检测，对应产品类别有：手机、平板电脑、数码相机、摄像机、电脑配件等

| 技术参数 / Parameters                                  |  |                        |                           |
|--|--|------------------------|---------------------------|
| 型号 Model   | T-1010a  | T-2010a                | T-3010a                   |
| 测量原理 Measurement Principle                         | 3D 白光 PSLM PMP （可编程结构光栅相位调制轮廓测量技术）   |                        |                           |
| 测量项目 Measurements                                  | 体积，面积，高度，XY 偏移，形状  |                        |                           |
| 检测不良类型 Detection of Non – Performing Types         | 漏印，少锡，多锡，连锡，偏移，形状不良  |                        |                           |
| 视野尺寸 FOV Size                                      | 26 X 20mm  |                        |                           |
| 精度 Accuracy  | XY 方向：10um；高度：0.37um   |                        |                           |
| 重复精度 Repeatability                                 | 高度：小于 1um（4 Sigma）；体积 / 面积：小于 1%（5 Sigma）  |                        |                           |
| 检测重复性 Gage R&R                                     | 远远小于 10%   |                        |                           |
| 检测速度 Inspection Speed                              | 1.5 秒 /FOV   |                        |                           |
| 检测头数量 Quantity of Inspection Head                  | Single Head  |                        |                           |
| 基准点检测时间 Mark–point Detection Time                  | 0.3 秒 / 个  |                        |                           |
| 最大检测高度 Maximun Measuring Height                    | $\pm 350\mu\text{m}$ （ $\pm 1200\mu\text{m}$ * 选件）   |                        |                           |
| 弯曲 PCB 最大测量高度 Maximun Measuring Height of PCB Warp | $\pm 5\text{mm}$   |                        |                           |
| 最小焊盘间距 Minimum Pad Spacing                         | 100um（焊盘高度为 150um 的焊盘为基准）  |                        |                           |
| 最小测量大小 Smallest Size Measurement                   | 长方形：150um；圆形：200um   |                        |                           |
| 最大 PCB 载板尺寸 Maximum Loading PCB Size               | X350 x Y250 mm   | X460 x Y350 mm         | X700 x Y600 mm            |
| 定动轨设置  | 左定轨  | 前定轨                    | 前定轨                       |
| 工程统计数据 Engineering Statistics                      | Histogram；Xbar–R Chart；Xbar–S Chart；CP&CPK；%Gage Repartability Data；SPI Daily/Weekly/Monthly Reports |                        |                           |
| Gerber 和 CAD 导入 Gerber & CAD Data Import           | 支持 Gerber 格式（274x，274d）；人工 Teach 模式；CAD X/Y，Part No.，Package Type 等导入                                |                        |                           |
| 操作系统支持 Operating System Support                    | Windows 7 Professional（32 位）   |                        |                           |
| 设备规格 Equipment Diemension and Weight               | 630 x 480 x 540mm；75KG   | 810 x 930 x 530mm；95KG | 1500 x 1100 x 600mm；145KG |
| 选配件 Optional                                       | 1D/2D Barcode 扫描枪；UPS 不间断电源；工作台（除 T-3010a 外）   |                        |                           |



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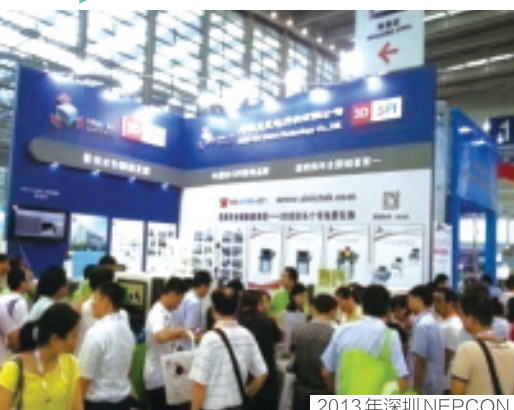




# WORKSHOP HONOR

## 展会

NEW TECHNOLOGY  
NEW DEVELOPMENT  
新技术引领新发展



2013年深圳NEPCON



2012年深圳NEPCON



2013年深圳电子博览会



2012年上海NEPCON



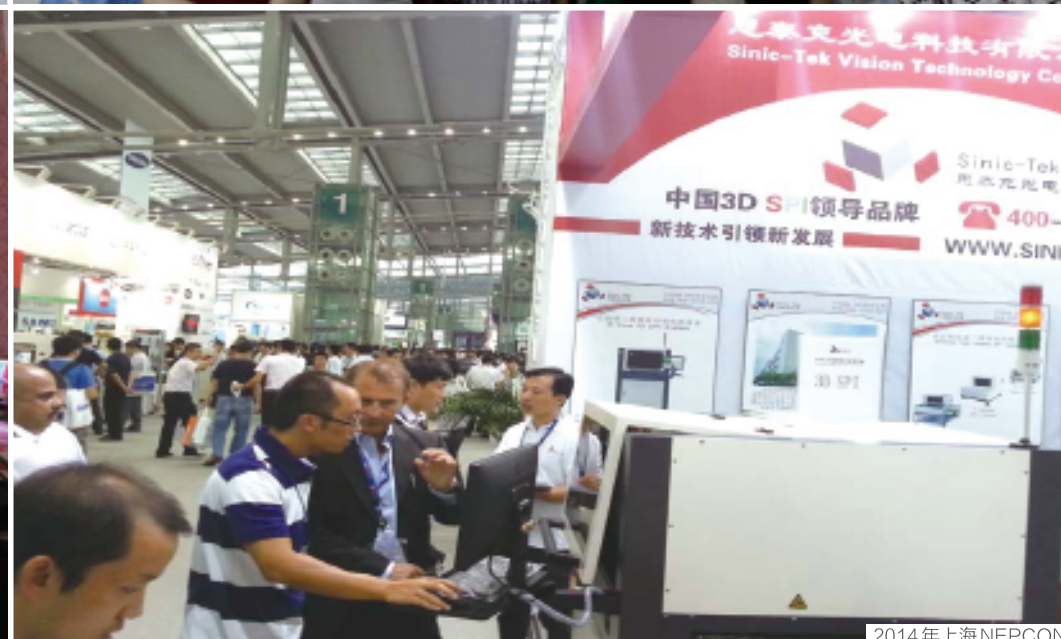
2017年思泰克智能上市答谢会暨2017迎新年会



2010年上海NEPCON



2015年深圳NEPCON



2014年上海NEPCON



2015年思泰克智能新品发布会



2017年上海NEPCON



2014年华南SMT学术年会



2015年上海电子展



# CUSTOMER SCENE

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ervice Promise: We Provide free repairing and software update after purchase for 12 months, as well as yearly maintenance. We provide free production trial ramp up use and calibration service.

根据仪器型号规格不同，参数会发生变化，由于持续开发产品，因此参数规格若有变化恕不另行通知，请以实物为准。

The parameters will be varying for different model and standard, as parameters are subject to change due to continuous development without prior notice. Please refer for actual product.



## NEW TECHNOLOGY NEW DEVELOPMENT

### 新技术引领新发展